



Inductors

RF chokes, SBC series

Series/Type: B82141A, B82141B

Date: March 2008

SBC choke (Small Bobbin Core)
Rated inductance 1 μH to 1000 μH
Rated current 55 mA to 725 mA

Construction

- Mini ferrite drum core
- Winding: enamel copper wire
- Flame-retardant lacquer coating

Features

- Small size
- Relatively high rated current
- Suitable for wave soldering
- RoHS-compatible

Applications

- RF blocking and filtering
- Decoupling and interference suppression
- For electronic household appliances, automotive and entertainment electronics

Terminals

- Central axial leads (B82141A)
- Radially bent to 5 mm lead spacing (B82141B)
- Base material CuAg0.1
- Hot-dipped with pure tin

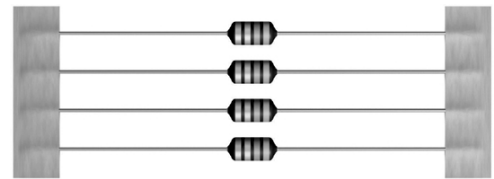
Marking

Inductance indicated by color bands to IEC 60062

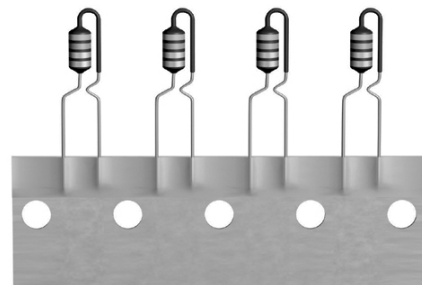
Delivery mode and packing units

- Taped, Ammo and reel packing
- Packing units:

	Ammo (pcs./pack.)	Reel (pcs./reel)
Axial	5000	5000
Radial	2500	2000



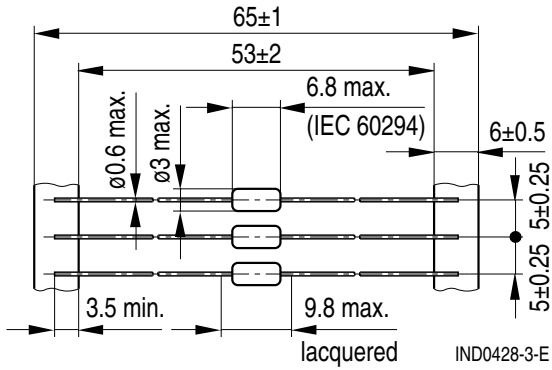
B82141A



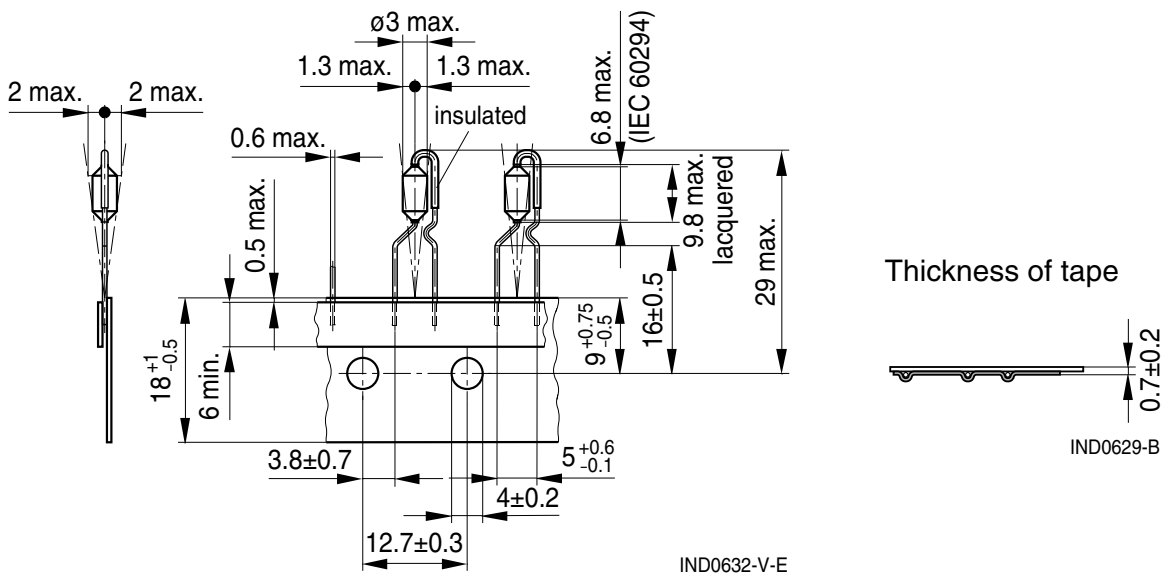
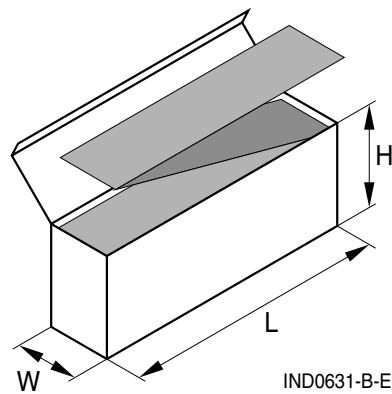
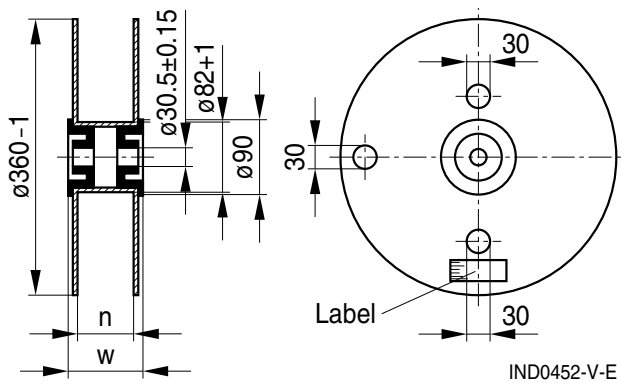
B82141B

Dimensional drawings
B82141A (axial leads, taped)

Dimensions in mm



Minimum lead spacing 10 mm

B82141B (central radial leads, taped)

Packing


n (mm): Axial 72 +1, radial 42 +1
 w (mm): Axial 84 max., radial 54 max.

L × W × H (max. mm):
 Axial: 310 × 75 × 120, radial: 340 × 50 × 210

Technical data and measuring conditions

Rated inductance L_R	Measured with LCR meter Agilent 4284A or impedance analyzer Agilent 4294A Measuring frequency: $L_R \leq 10 \mu\text{H}$ = 1 MHz $10 \mu\text{H} < L_R \leq 4700 \mu\text{H}$ = 100 kHz Measuring current: $\leq 1 \text{ mA}$ Measuring temperature: 20 °C
Q factor Q_{\min}	Measured with precision impedance analyzer Agilent 4294A, 20 °C
Rated temperature T_R	40 °C
Rated current I_R	Maximum permissible DC current at rated temperature
Inductance decrease $\Delta L/L_0$	$\leq 10\%$ (referred to initial value) at I_R , 20 °C
DC resistance R_{\max}	Measured at 20 °C
Resonance frequency $f_{\text{res},\min}$	Measured with Agilent 4294A or 8753ES, 20 °C
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: (245 ±5) °C, (3 ±0.3) s Wetting of soldering area $\geq 90\%$ (to IEC 60068-2-20, test Ta)
Resistance to soldering heat	(260 ±5) °C, 10 s (to IEC 60068-2-20, test Tb)
Tensile strength of leads	$\geq 20 \text{ N}$ (to IEC 60068-2-21, test Ua)
Climatic category	55/125/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +125 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 0.22 g

⚠ Mounting information

When bending the leads, take care that the start-of-winding areas at the face ends (protected by glue and lacquer) are not subjected to any mechanical stress.

Characteristics and ordering codes

L_R μH	Tolerance ¹⁾	Q_{\min}	f_Q MHz	I_R mA	R_{\max} Ω	$f_{\text{res, min}}$ MHz	Ordering code ²⁾ (reel packing) ³⁾
1.0	$\pm 10\% \triangleq K$	40	7.96	725	0.19	180	B82141+1102K000
1.2		40	7.96	700	0.20	160	B82141+1122K000
1.5		40	7.96	670	0.22	155	B82141+1152K000
1.8		45	7.96	660	0.23	145	B82141+1182K000
2.2		45	7.96	630	0.25	130	B82141+1222K000
2.7		45	7.96	610	0.27	110	B82141+1272K000
3.3		50	7.96	580	0.30	90	B82141+1332K000
3.9		50	7.96	560	0.32	70	B82141+1392K000
4.7		50	7.96	530	0.36	60	B82141+1472K000
5.6		50	7.96	510	0.38	50	B82141+1562K000
6.8		50	7.96	480	0.43	40	B82141+1682K000
8.2		50	7.96	450	0.52	30	B82141+1822K000
10		55	2.52	410	0.60	25	B82141+1103K000
12		55	2.52	385	0.67	20	B82141+1123K000
15		55	2.52	365	0.74	17	B82141+1153K000
18		55	2.52	350	0.81	14	B82141+1183K000
22		55	2.52	335	0.90	12	B82141+1223K000
27		55	2.52	315	1.00	11	B82141+1273K000
33		55	2.52	300	1.12	10	B82141+1333K000
39	55	2.52	285	1.21	8.5	B82141+1393K000	

1) Closer tolerances on request.

2) Replace the + by code letter »A« for axial taping or by »B« for radial taping.

3) For Ammo pack the last digit has to be a »9«. Example: B82141A1102K009

Characteristics and ordering codes

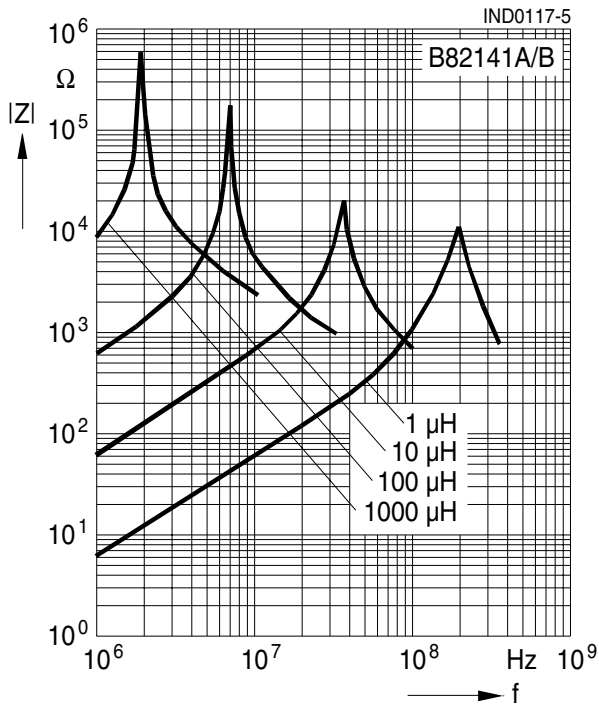
L_R μH	Tolerance ¹⁾	Q_{\min}	f_Q MHz	I_R mA	R_{\max} Ω	$f_{\text{res, min}}$ MHz	Ordering code ²⁾ (reel packing) ³⁾
47	$\pm 5\% \triangleq J$	55	2.52	200	2.40	7.7	B82141+1473J000
56		55	2.52	195	2.60	6.8	B82141+1563J000
68		55	2.52	185	2.90	5.7	B82141+1683J000
82		55	2.52	175	3.20	5.5	B82141+1823J000
100		60	0.796	170	3.50	5.3	B82141+1104J000
120		60	0.796	160	3.80	5.0	B82141+1124J000
150		60	0.796	150	4.30	4.6	B82141+1154J000
180		60	0.796	135	5.30	4.2	B82141+1184J000
220		60	0.796	130	5.80	3.8	B82141+1224J000
270		60	0.796	115	7.80	3.2	B82141+1274J000
330		60	0.796	105	9.10	3.0	B82141+1334J000
390		60	0.796	95	11.0	2.7	B82141+1394J000
470		60	0.796	90	12.0	2.3	B82141+1474J000
560		60	0.796	75	16.5	2.2	B82141+1564J000
680		60	0.796	65	22.0	2.0	B82141+1684J000
820		60	0.796	60	25.0	1.8	B82141+1824J000
1000	60	0.796	55	33.0	1.5	B82141+1105J000	

1) Closer tolerances on request.

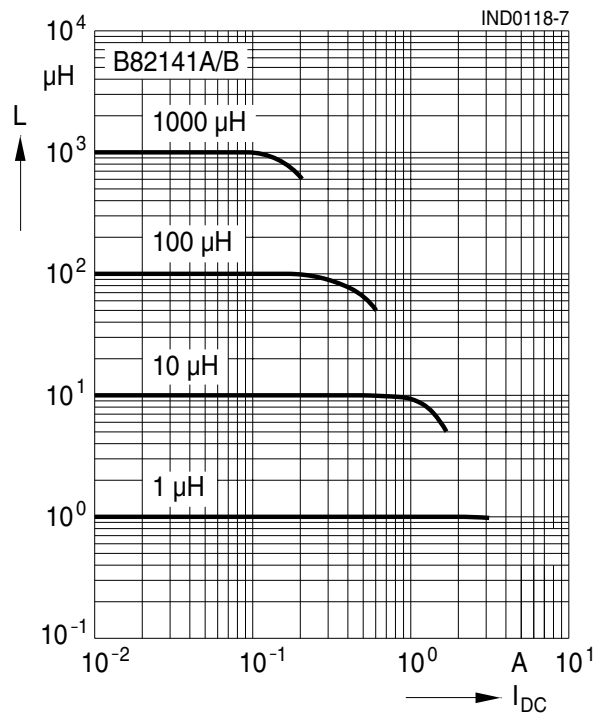
2) Replace the + by code letter »A« for axial taping or by »B« for radial taping.

3) For Ammo pack the last digit has to be a »9«. Example: B82141B1473J009

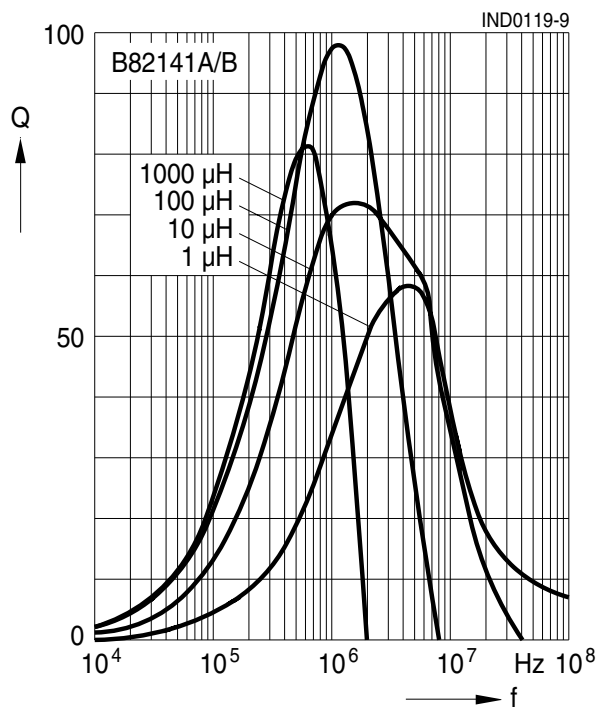
Impedance |Z| versus frequency f
 measured with impedance analyzer Agilent 4294A or S-parameter network analyzer Agilent 8753ES, typical values at 20 °C



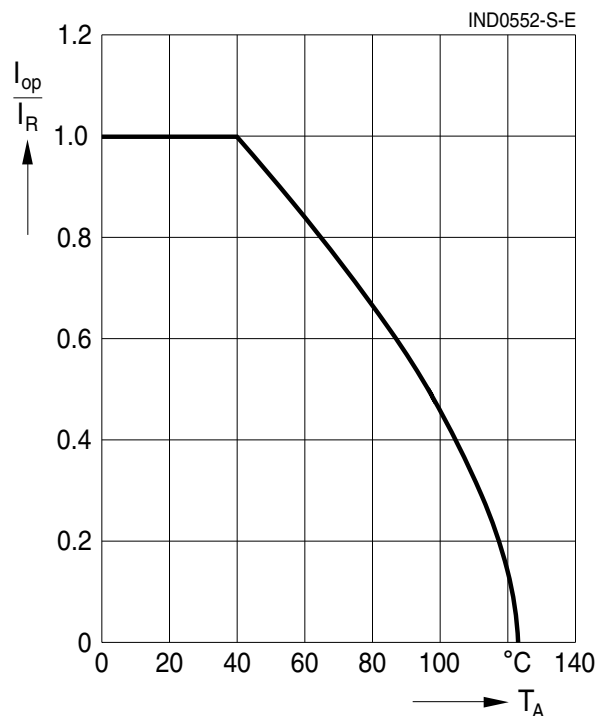
Inductance L versus DC load current I_{DC}
 measured with LCR meter Agilent 4284A, typical values at 20 °C



Q factor versus frequency f
 measured with impedance analyzer Agilent 4294A, typical values at 20 °C



Current derating I_{op}/I_R versus ambient temperature T_A
 (rated temperature T_R = 40 °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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